IPC ASSOCIATION COL	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard  http://www.ipc.org/IPC-175x  Form Typ Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information			
upplier In	nformation								·						
Company name*			Company unique ID			J	Unique ID Authority					Response Date*			
nsemi											2024-04	2024-04-30			
Contact Name	ne	Title - Contact			I	Phone - Contact*				Email - Contact*					
Product-Env	y-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized R	Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env	y-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Re	Requester Item Number		Number	Mfr Item Name			Effective Date	Version	ion Manufacturing Site			Weight*	UOM	Unit Type	
		LC88F58B0AU- 16-bit Microcontro SQFPH 16-bit Microcontro		ller		2024-04-30			400.0	mg	Each				
Ianufactu	uring Proccess Informa	ation													
Tei	Terminal Plating / Grid Array Material To			Germinal Base Alloy J-STD-020 MSL			ng Peak Process Body Temperature Max Time at Peak				k Tempera	ture Num	ber of Reflow Cyc	eles	
contains Bi		CU Alloy 3				260		C	30	seco	nds 3				
omments															
<b>ITENTION</b>	N: MSL 3 Rated item requir	res Bake and D	ry Pack (afte	r electrical test)											
or more info	ormation regarding materia	al composition	nlease refer t	n nage 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have not independently verified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier p											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.29	mg	Supplier	Silicon (Si)	7440-21-3		6.2667	mg
			Supplier	Polyimide	Proprietary Data		0.0233	mg
Die Attach	1.56	mg	Supplier	Silver (Ag)	7440-22-4		1.0614	mg
			Supplier	Epoxy resins	129915-35-1		0.4512	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.034	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0134	mg
Lead Frame	237.42	mg	Supplier	Silver (Ag)	7440-22-4		1.2821	mg
			Supplier	Zinc (Zn)	7440-66-6		0.2951	mg
			Supplier	Iron (Fe)	7439-89-6		5.5492	mg
			Supplier	Copper (Cu)	7440-50-8		230.0987	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1949	mg
Mold Compound-Black	149.01	mg		Epoxy resin	proprietary data		14.901	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		11.1757	mg
			Supplier	Carbon Black (C)	1333-86-4		0.745	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		122.1882	mg
Plating	4.2	mg	В	Bismuth (Bi)	7440-69-9		0.0252	mg
			Supplier	Tin (Sn)	7440-31-5		4.1748	mg
Wire Bond - Au	1.52	mg	Supplier	Gold (Au)	7440-57-5		1.52	mg